RATING VOLTAGE 250 V AC OPERATION STREAMS AND COUNTRY CAN DESCRIPTIONS SPECIFICATIONS TEM	APPLICABLE STANDARI										
CUNREM	RATING	<u> </u>		250 V AC	250 V AC TEN		TURE RANG	E	-30 °C TO +85 °C(I	NOTE	(1)
TITEM TEST METHOD REQUIREMENTS OT AT CONSTRUCTION GENERAL EXAMINATION [VISUALLY AND BY MEASURING INSTRUMENT.] MARKING CONFIRMED VISUALLY. ELECTRIC CHARACTERISTICS CONTACT RESISTANCE 100 ma (DC OR 100 Hz). NO MAX. ** × ** × ** × ** × ** × ** × ** * **				2A		1			-10 °C TO +60 °C(N		2)
CONSTRUCTION CENERAL EXAMINATION VISUALLY AND BY MEASURING INSTRUMENT. MARKING CONFIRMED VISUALLY. ELECTRIC CHARACTERISTICS CONTACT RESISTANCE 100 mA (DC OR 1000 Hz). INSULATION RESISTANCE 100 mA (DC OR 1000 Hz). INSULATION RESISTANCE 100 mA (DC OR 1000 Hz). INSULATION RESISTANCE 100 mA (DC OR 1000 Hz). MECHANICAL CHARACTERISTICS MECHANICAL OPERATION 50 TIMES INSERTIONS AND EXTRACTIONS. WECHANICAL OPERATION 50 TIMES TO 55 Hz. SINGLE AMPLITUDE 1, 15, 15, 15, 15, 15, 15, 15, 15, 15,	SPECIFICATIONS										
CENERAL EXAMINATION VISUALLY AND BY MEASURING INSTRUMENT. ACCORDING TO DRAWING. X X X X X X X X X	1	ГЕМ	TEST METHOD				REQUIREMENTS			QT	АТ
MARKING	CONSTRUCTION						•				
MARKING	GENERAL E	GENERAL EXAMINATION		VISUALLY AND BY MEASURING INSTRUMENT.			ACCORDING TO DRAWING.			×	×
SUNTACT RESISTANCE 100 mA (DC OR 1000 Hz). 30 mΩ MAX. X −	MARKING	MARKING		CONFIRMED VISUALLY.			†				
INSULATION RESISTANCE SO 0 V DC. 1000 MΩ MIN. X V V V V V V V V V	ELECTRIC CHARA		CTERISTICS			•					
NSULATION RESISTANCE S00 V DC. 1000 MΩ MIN. X	CONTACT	CONTACT RESISTANCE		100 mA (DC OR 1000 Hz).			30 mΩ MAX.				_
VOLTAGE PROOF	INSULATION RESISTANCE		500 V DC.			1000	1000 MΩ MIN.				_
MECHANICAL CHARACTERISTICS MECHANICAL OPERATION 50 TIMES INSERTIONS AND EXTRACTIONS 0 CONTACT RESISTANCE: 30 m/2 MAX. 0 NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 0 NO DAMAGE, CRACK OR LOOSEN	VOLTAGE PROOF		650 V AC FOR 1 min.			NO F	NO FLASHOVER OR BREAKDOWN.				_
MECHANICAL OPERATION 50 TIMES INSERTIONS AND EXTRACTIONS. 0. CONTACT RESISTANCE: 30 mc MAX. 0. NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 0. NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 0. NO DESCRIPTION OF PULSE 11 ms AT 3 TIMES OF PARTS. 0. NO DELECTRICAL DISCONTINUITY OF 1 μs. 0. NO DELECTRICAL DISCONTINUITY OF 1 μs. 0. NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 0. NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS. 0. NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS. 0. NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS. 0. NO STRENGTH ON CONTACT. 0. NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS. 0. NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS. 0. NO STRENGTH ON CONTACT. 0. NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS. 0. NO STRENGTH ON CONTACT. 0. NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS. 0. NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS. 0. NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS. 0. NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS. 0. NO DEFORMATION OF CASE OF EXCESSIVE	MECHAI	VICAL CH	L ARACTERISTICS								
1, μs NO DAMAGE, CRACK OR LOOSENESS X _						2 N	② NO DAMAGE, CRACK OR LOOSENESS				_
SHOCK	VIBRATION		· '			1	1 μs. ② NO DAMAGE, CRACK OR LOOSENESS				-
DAMP HEAT (STEADY STATE) EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h. © CONTACT RESISTANCE: 30 mΩ MAX. © INSULATION RESISTANCE: 1000 MΩ MIN. © INSULATION RESISTANCE: 30 mΩ MAX. ▼ - MIN. ■ NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF PARTS. NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE EXC	SHOCK					MEGI					-
DAMP HEAT (STEADY STATE) EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h. © CONTACT RESISTANCE: 30 mΩ MAX. © INSULATION RESISTANCE: 1000 MΩ MIN. © INSULATION RESISTANCE: 30 mΩ MAX. ▼ - MIN. ■ NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF PARTS. NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE EXC	ENVIRO	NMENTAL	CHAR	ACTERISTICS						-	<u> </u>
RAPID CHANGE OF TEMPERATURE −55→+5TO+35→5TO+35*C			EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.			2 II 3 N	② INSULATION RESISTANCE:500 MΩMIN. ③ NO DAMAGE, CRACK OR LOOSENESS				-
RESISTANCE TO SOLDERING (FLOW) SOLDER TEMPERATURE: 280 ± 3°C FOR IMMERSION, DURATION: 10 sec. @MANUAL SOLDERING SOLDERING SOLDERING IRON TEMPERATURE: 290 ± 10°C SOLDERING IRON TEMPERATURE: 290 ± 10°C SOLDERING TIME: 2 sec. NO STRENGTH ON CONTACT. SOLDERABILITY SOLDERED AT SOLDER TEMPERATURE, 240°C SOLDER SHALL COVER A MINIMUM OF FOR IMMERSION DURATION, 3 sec. PEMARKS NOTE::NOLUDE THE TEMPERATURE RISING BY CURRENT. NOTE2:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE PCB ON BOARD, AFTER PCB BOARD, OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERIM STORAGE DURING TRANSPORTATION. COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE Unless otherwise specified, refer to JIS C 5402. APPROVED TY. DMA 06.03.22 CHECKED HK. UMEHARA 06.03.22 CHECKED HK. UMEHARA 06.03.22 DESIGNED TS. KUMAZAWA 06.03.27 DESIGNED TS. K			TIME	TIME 30→ 5 TO 15 → 30→5TO15 min			 ① CONTACT RESISTANCE: 30 mΩ MAX. ② INSULATION RESISTANCE: 1000 MΩ MIN. ③ NO DAMAGE, CRACK OR LOOSENESS 				_
SOLDERING HEAT SOLDER TEMPERATURE: 280±3°C FOR IMMERSION, DURATION: 10 sec. @MANUAL SOLDERING SOLDERING IRON TEMPERATURE: 290±10°C SOLDERING TIME: 2 sec. NO STRENGTH ON CONTACT. SOLDER SHALL COVER A MINIMUM OF FOR IMMERSION DURATION, 3 sec. REMARKS NOTE::NOCLUDE THE TEMPERATURE RISING BY CURRENT. NOTE::NOCLUDE THE TEMPERATURE RISING BY CURRENT. NOTE::APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE PCB ON BOARD, AFTER PCB BOARD, OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERIM STORAGE DURING TRANSPORTATION. COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED APPROVED TY. DMA DES. 01.03.22 DESIGNED TY. DMA DES. 01.03.22 DESIGNED DESIGNED TY. DMA DES. 03.22 DESIGNED TY. DMA DES. 04.03.22 DES. 04.0	RESISTANO	DECISTANCE TO					I .				
SOLDERING TIME: 2 sec. NO STRENGTH ON CONTACT. SOLDERABILITY SOLDERED AT SOLDER TEMPERATURE,240°C FOR IMMERSION DURATION,3 sec. SOLDER SHALL COVER A MINIMUM OF FOR IMMERSION DURATION,3 sec. SOLDER SHALL COVER A MINIMUM OF FOR IMMERSION DURATION,3 sec. SOLDER SHALL COVER A MINIMUM OF 95% OF THE SURFACE BEING IMMERSED X - REMARKS NOTE1:INCLUDE THE TEMPERATURE RISING BY CURRENT. NOTE2:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE PCB ON BOARD, AFTER PCB BOARD, OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERIM STORAGE DURING TRANSPORTATION. COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED APPROVED TY. DMA 16.03.22 CHECKED HK. UMEHARA 16.03.22 DRAWN AK. MIURA 16.03.17 Note QT:Qualification Test AT:Assurance Test X:Applicable Test DRAWING NO. ELC4-020817-01			SOLDER TEMPERATURE : 260 ± 3 °C FOR			EXC	EXCESSIVE LOOSENESS OF THE				_
FOR IMMERSION DURATION,3 sec. 95% OF THE SURFACE BEING IMMERSED × _ REMARKS NOTE1:INCLUDE THE TEMPERATURE RISING BY CURRENT. NOTE2:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE PCB ON BOARD, AFTER PCB BOARD, OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERIM STORAGE DURING TRANSPORTATION. COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE Unless otherwise specified, refer to JIS C 5402. APPROVED TY. OMA 06.03.22 CHECKED HK. UMEHARA 06.03.22 DESIGNED TS. KUMAZAWA 06.03.22 DRAWN AK. MIURA 06.03.17 Note QT:Qualification Test AT:Assurance Test X:Applicable Test DRAWING NO. ELC4-020817-01 FIG. SPECIFICATION SHEET PART NO. DF11-8DP-2DSA (01)			SOLDERING IRON TEMPERATURE : 290 ± 10 °C SOLDERING TIME : 2 sec.								
REMARKS NOTE1:INCLUDE THE TEMPERATURE RISING BY CURRENT. NOTE2:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE PCB ON BOARD, AFTER PCB BOARD, OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERIM STORAGE DURING TRANSPORTATION. COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE Unless otherwise specified, refer to JIS C 5402. APPROVED TY.OMA 06.03.22 CHECKED HK.UMEHARA 06.03.22 DESIGNED TS.KUMAZAWA 06.03.22 DRAWN AK.MIURA 06.03.17 Note QT:Qualification Test AT:Assurance Test X:Applicable Test DRAWING NO. ELC4-020817-01 SPECIFICATION SHEET PART NO. DF11-8DP-2DSA (01)	SOLDERABILITY			,							
Unless otherwise specified, refer to JIS C 5402. APPROVED	NOTE1:INCL NOTE2:APPI ON E	UDE THE TEM LY TO THE CO SOARD, AFTER	PERATURE NDITION O	E RISING BY CURRENT. OF LONG TERM STORAGE FO RD,OPERATING TEMPERATL	R UNUSED	PRODUCT	S BEFORE	РСВ		*	-
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RS SPECIFICATION SHEET PART NO. DF11-8DP-2DSA (01)	Note QT:C	Note QT:Qualification Test AT:Assurance Test X:Applicable Test D									
			SPECIFICATION SHEET			PART NO.		D	DF11-8DP-2DSA (01)		
	1		HIROSE ELECTRIC CO., LTD.			CODE NO	CL543-0519-0-01		\triangle	1/1	